

Applicable standard					
Rating	Operating temperature range	-35°C to +85°C(Note1)	Storage temperature range	-10°C to +60°C(Note3)	
	Operating humidity range	20 % to 80 % (Note2)	Storage humidity range	40 % to 70 %(Note3)	
	Current	1 A	Voltage	150 V AC/DC	
Specifications					
Item		Test method	Requirements	QT	AT
Construction					
General examination		Visually and by measuring instrument.	According to drawing.	X	X
Marking		Confirmed visually.		X	X
Electric characteristics					
Contact resistance	100 mA (DC or 1000 Hz).	30 mΩ MAX.	X	—	
Contact resistance Millivolt level method.	20 mV MAX, 1 mA (DC or 1000 Hz).				
Insulation resistance	100 V DC.	500 MΩ MIN.	X	—	
Voltage proof	500 V AC for 1 min.	No flashover or breakdown.	X	—	
Mechanical characteristics					
Mechanical operation	50 times insertions and extractions.	① Contact resistance: 30 mΩ MAX. ② No damage, crack or looseness of parts.	X	—	
Vibration	Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 2 h, for 3 directions.	① No electrical discontinuity of 1μs. ② No damage, crack or looseness of parts.	X	—	
Shock	490 m/s ² duration of pulse 11 ms at 3 times for 3 directions.		X	—	
Environmental characteristics					
Rapid change of temperature	Temperature -55→ 5 to 35→ +85→ 5 to 35 °C Time 30→ 10 to 15→ 30→ 10 to 15 min. Under 5 cycles.	① Contact resistance: 30mΩ MAX. ② Insulation resistance: 500 MΩ MIN. ③ No damage, crack or looseness of parts.	X	—	
Damp heat (Steady state)	Exposed at 40 ± 2 °C, 90 to 95 %, 96 h.				
Resistance to soldering heat	1) Reflow soldering « Reflow area » Max 250°C 10 sec max 230°C min 60 sec max « Preheating area » 170°C to 190°C 60 sec to 120 sec Put through in reflow furnace twice. Leave in ambient temperature and Humidity for 1 hour. Connector temperature to be Ambient for second reflow. 2) Manual soldering Soldering iron temperature :350±5 °C, Soldering time : 5±1 sec. No strength on contact.	No deformation of case of excessive looseness of the terminals.	X	—	
Solderability	Soldering temperature : 235±5°C Duration of immersion : soldering, for 3 sec.	Solder shall cover a minimum of 95 % of the surface being immersed.	X	—	
Remarks Note 1: Include the temperature rising by current. Note 2: No condensing Note 3: Apply to the condition of long term storage for unused products before mounted on PCB. After mounted on PCB, operation temperature and humidity range is applied for interim storage during transportation.					
	Count	Description of revisions	Designed	Checked	Date
△					
Unless otherwise specified, refer to IEC 60512.			Approved	HS. OKAWA	20190311
			Checked	SZ. ONO	20190311
			Designed	HK. HAYASHI	20190311
			Drawn	SK. CHIBA	20190311
Note QT:Qualification Test AT:Assurance Test X:Applicable Test		Drawing no.	ELC-160335-56-00		
HRS	Specification sheet		Part no.	DF14-6P-1. 25H (56)	
	Hirose electric co., ltd.		Code no.	CL538-0025-5-56	△ 1/1